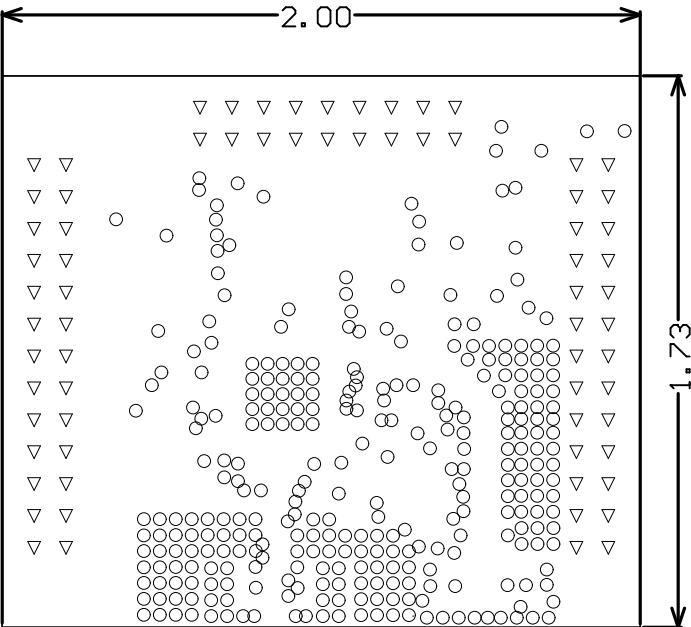


Fabrication Notes:

- 1. All dimensions in inches. Tolerance = +/- 0.005 unless noted otherwise
- 2. All materials: laminates, resins, metallizations and soldermask to be compliant to EU RoHS directive 2002/95/EC IAW SP-12509-01.
- 3. 370 HR FR-4 or similar grade glass epoxy.
- 4. Tg > 170 degrees celcius, glass transition temperature.
- 5. TD > 350 degrees celcius, thermal decomposition.
- 6. Er = 4.0 +/- 5% @ 2.5GHz.
- 7. Minimum flammability rating UL94V-0, maximum dissipation factor 0.025.
- 8. Adjust prepreg for 0.062 , +/- 0.003 finished thickness measured over soldermask.
- 9. Copper thickness 0.0014 , (1 oz).
- 10. Hole size tolerance = +/- 0.003 unless noted otherwise.
- 11. Hole centers and pad centers to be concentric within 0.002 .
- 12. Drill chart dimensions are drill sizes and not finished hole sizes.
- 13. Finish - immersion gold over nickel. No exposed bare copper permitted.
- 14. Thieving not allowed on layer 1.
- 15. Solder mask over bare copper, LPI class 2 gen. industrial registration +/- 0.004 .
- 16. No coverage on solder pads permitted.
- 17. Refer to soldermask gerbers for tenting of vias.
- 18. White silkscreen legend over red soldermask - both sides.
- 19. Manufacturer icons not permitted on the silkscreen top layer.
- 20. PCB serialization/panel placement ID on silkscreen bottom.
- 21. Full electrical test against IPC-356A netlist.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.40mil	3.5	
4	Top Layer	Copper	1.40mil		
5	Dielectric1	HR370	16.00mil	4	
6	Gnd Layer 2	Copper	1.40mil		
7	Dielectric2	HR370	24.00mil	4	
8	Power Layer 3	Copper	1.40mil		
9	Dielectric3	HR370	16.00mil	4	
10	Bottom Layer	Copper	1.40mil		
11	Bottom Solder	Solder Resist	0.40mil	3.5	
12	Bottom Overlay				
13	Bottom Paste				

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	313	10mil (0.254mm)	PTH	Round
▽	70	40.157mil (1.02mm)	PTH	Round
	383 Total			

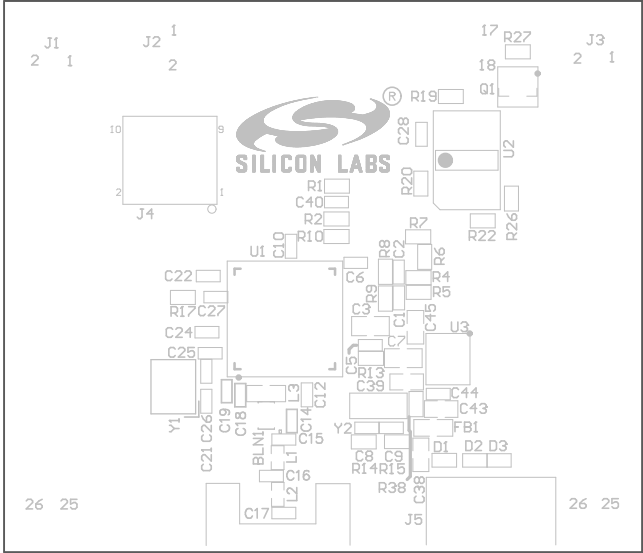
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617-951-0200

TITLE: EM359x Ref Des, Ceramic Balun, USB, 4-layer	
FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Drill Drawing	DATE: 3/25/2015





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617-951-0200

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FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Top Overlay	DATE: 3/25/2015

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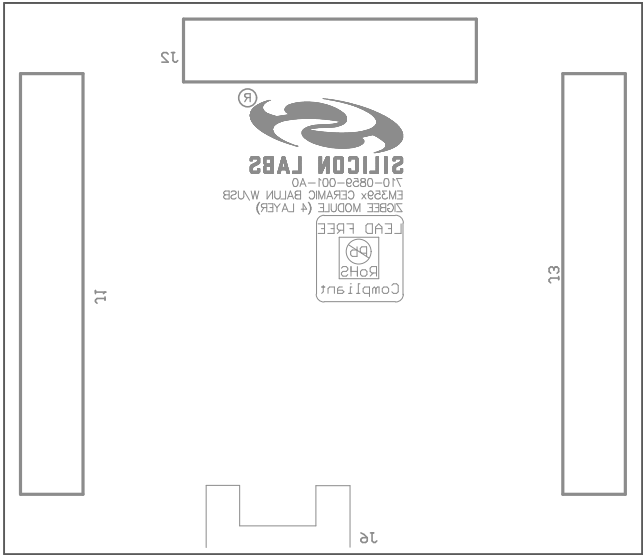
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FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Bottom Overlay	DATE: 3/25/2015

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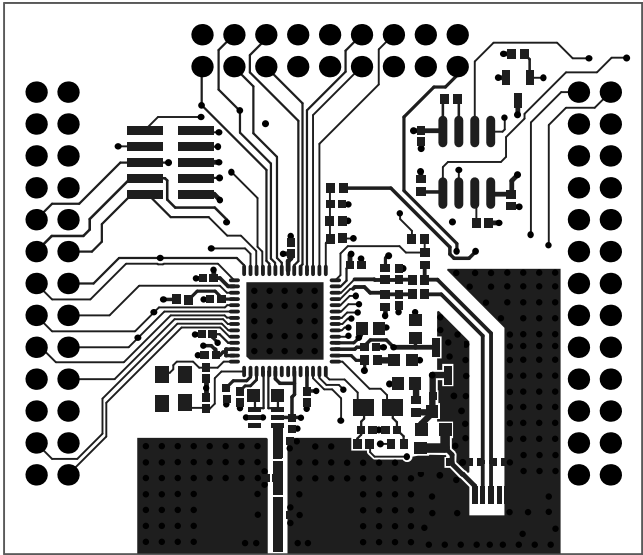
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TITLE:  
EM359x Ref Des, Ceramic Balun, USB, 4-layer

FILE NAME:  
EM359x\_REF\_DES\_CER\_USB.PcbDoc

Board NO.:  
EM359x\_REF\_DES\_CER\_USB

REV:  
A0

Layer:  
Top Layer

DATE:  
3/25/2015

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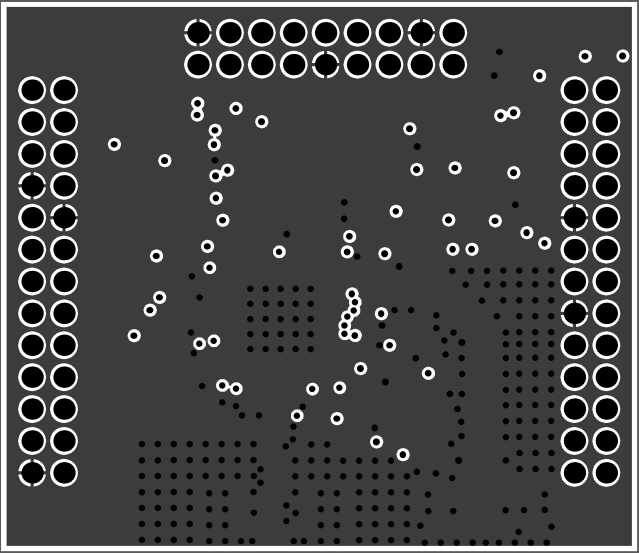
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EM359x Ref Des, Ceramic Balun, USB, 4-layer

FILE NAME:  
EM359x\_REF\_DES\_CER\_USB.PcbDoc

Board NO.:  
EM359x\_REF\_DES\_CER\_USB

REV:  
A0

Layer:  
Gnd Layer 2

DATE:  
3/25/2015

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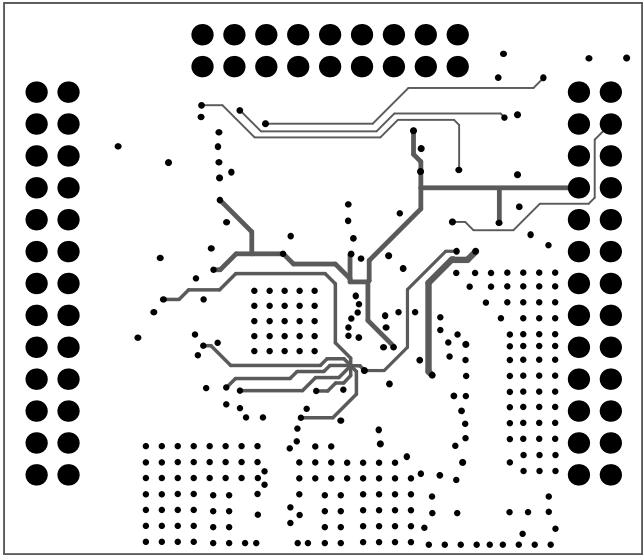
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TITLE: EM359x Ref Des, Ceramic Balun, USB, 4-layer	
FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Power Layer 3	DATE: 3/25/2015

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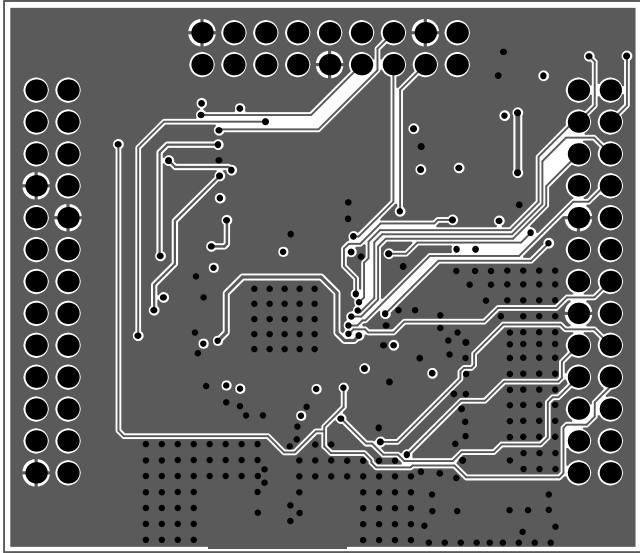
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TITLE: EM359x Ref Des, Ceramic Balun, USB, 4-layer	
FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Bottom Layer	DATE: 3/25/2015

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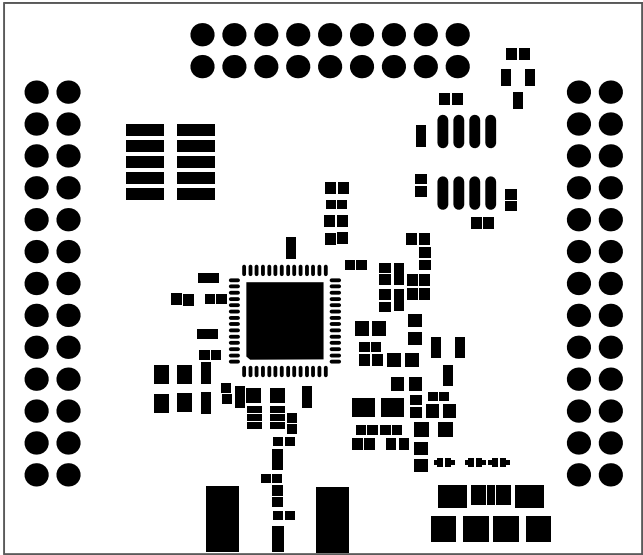
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TITLE:  
EM359x Ref Des, Ceramic Balun, USB, 4-layer

FILE NAME:  
EM359x\_REF\_DES\_CER\_USB.PcbDoc

Board NO.:  
EM359x\_REF\_DES\_CER\_USB

REV:  
A0

Layer:  
Top Solder

DATE:  
3/25/2015

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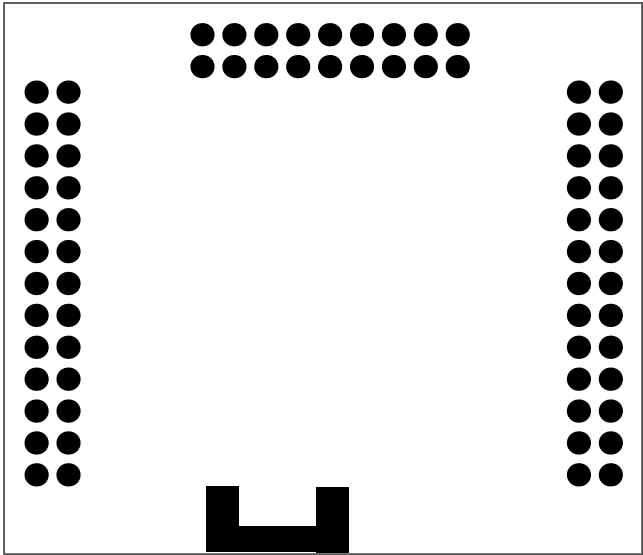
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TITLE: EM359x Ref Des, Ceramic Balun, USB, 4-layer	
FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Bottom Solder	DATE: 3/25/2015

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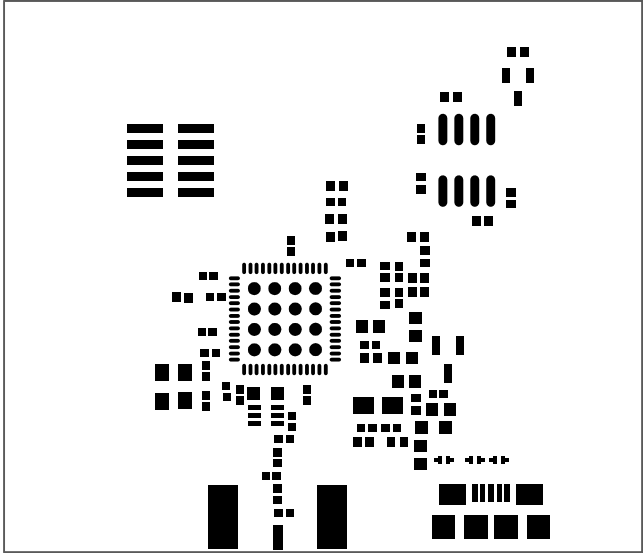
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FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Top Paste	DATE: 3/25/2015

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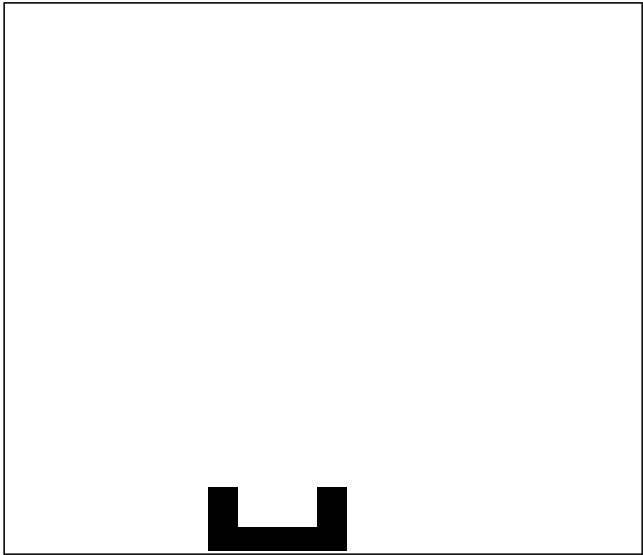
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FILE NAME: EM359x_REF_DES_CER_USB.PcbDoc	
Board NO.: EM359x_REF_DES_CER_USB	REV: A0
Layer: Bottom Paste	DATE: 3/25/2015

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